

## AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior versions, and listings, of claims in the application:

### Listing of Claims:

1 (currently amended). A high-frequency switching module ~~primarily~~ including a switching circuit and a filtering circuit, comprising:

a multi-layer assembly having a plurality of dielectric sheets of layers placed one over ~~the~~ other another;

a plurality of high-frequency terminals provided on outer surfaces of the multi-layer assembly;

said switching circuit being formed with circuit electrodes in the layers of said multi-layer assembly ~~[[,]]~~ having ~~one~~ a first end thereof connected to a first high-frequency terminal of said plurality of high-frequency terminals; and

said filtering circuit being formed with circuit electrodes in the layers of said multi-layer assembly ~~[[,]]~~ having ~~one~~ a first end thereof connected to ~~the other~~ a second end of said switching circuit ~~and the other~~ a second end thereof being connected to a second high-frequency terminal of said plurality of high-frequency terminals,

wherein said plurality of high-frequency terminals are provided on a mounting side surface of said multi-layer assembly while lateral sides of said multi-layer assembly are not provided with any electrode for said high-frequency terminals.

2 (canceled).

3 (canceled).

4 (currently amended). The high-frequency switching module according to claim 1, wherein each of the high-frequency terminals is arranged extending along ~~the~~ an outer edge of the mounting side surface of the multi-layer assembly so that each electrode width at the outer edge of ~~said the~~ the multi-layer assembly is greater than that at ~~the~~ an inner region of ~~the same the~~ the multi-layer assembly.

5 (currently amended). The high-frequency switching module according to claim 4, wherein the high-frequency terminals ~~are formed of~~ have a substantially  $[[a]]$  D character shape.

6 (currently amended). The  $[[A]]$  high-frequency switching module according to claim  $[[4]]$  including a switching circuit and a filtering circuit, comprising:

a multi-layer assembly having a plurality of dielectric sheets of layers placed one over another;

a plurality of high-frequency terminals provided on outer surfaces of the multi-layer assembly;

said switching circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a first high-frequency terminal of said plurality of high-frequency terminals;  
and

said filtering circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a second end of said switching circuit, a second end thereof being connected to a second high-frequency terminal of said plurality of high-frequency terminals.

wherein said plurality of high-frequency terminals are provided on a mounting side surface of said multi-layer assembly while lateral sides of said multi-layer assembly are not provided with any electrode for said high-frequency terminals, wherein the high-frequency terminals are positioned as being spaced by a given predetermined distance from the outer edge of the multi-layer assembly.

7 (currently amended). The [[A]] high-frequency switching module according to claim 1, including a switching circuit and a filtering circuit, comprising:

a multi-layer assembly having a plurality of dielectric sheets of layers placed one over another;

a plurality of high-frequency terminals provided on outer surfaces of the multi-layer assembly;

said switching circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a first high-frequency terminal of said plurality of high-frequency terminals; and

said filtering circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a second end of said switching circuit, a second end thereof being connected to a second high-frequency terminal of said plurality of high-frequency terminals,

wherein said plurality of high-frequency terminals are provided on a mounting side surface of said multi-layer assembly while lateral sides of said multi-layer assembly are not provided with any electrode for said high-frequency terminals, wherein said multi-layer assembly has having a rectangular four-sided outer shape and has having connection terminals provided at

corners of the mounting side surface thereof for external connection reinforcement.

8 (canceled).

9 (currently amended). The [[A]] high-frequency switching module according to claim 8, including a switching circuit and a filtering circuit, comprising:

a multi-layer assembly having a plurality of dielectric sheets of layers placed one over another;

a plurality of high-frequency terminals provided on outer surfaces of the multi-layer assembly;

said switching circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a first high-frequency terminal of said plurality of high-frequency terminals;  
and

said filtering circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a second end of said switching circuit, a second end thereof being connected to a second high-frequency terminal of said plurality of high-frequency terminals,

wherein said plurality of high-frequency terminals are provided on a mounting side surface of said multi-layer assembly while lateral sides of said multi-layer assembly are not provided with any electrode for said high-frequency terminals, said multi-layer assembly having a rectangular four-sided outer shape and connection terminals provided at an inner region of the mounting side surface for external connection reinforcement, wherein the connection terminals are being positioned at substantially the a center of the mounting side surface of the multi-layer assembly.

10 (original). The high-frequency switching module according to claim 9, wherein the connection terminals are positioned in symmetry with respect to substantially the center of the mounting side surface of the multi-layer assembly.

11 (canceled).

12 (canceled).

13 (canceled).

14 (currently amended). A high-frequency apparatus, comprising:  
a high-frequency switching module ~~defined in~~ according to claim 1; and  
a circuit board on which the high-frequency switching module is mounted, wherein  
lands provided on said circuit board are arranged smaller in size than the high-frequency terminals of said high-frequency switching module.

15 (currently amended). A high-frequency switching module ~~primarily~~ including a switching circuit and a filtering circuit, comprising:

a multi-layer assembly having a plurality of dielectric sheets of layers placed one over the ~~other~~ another;

a plurality of high-frequency terminals provided on outer surfaces of the multi-layer assembly;

said switching circuit being formed with circuit electrodes in the layers of said multi-layer assembly ~~[[,]]~~ having ~~one~~ a first end thereof connected to a first high-frequency terminal of said plurality of high-frequency terminals; and

said filtering circuit being formed with circuit electrodes in the layers of said multi-layer

assembly [[,]] having ~~one~~ a first end thereof connected to ~~the other~~ a second end of said switching circuit ~~and the other~~ , a second end thereof being connected to a second high-frequency terminal of said plurality of high-frequency terminals,

wherein said plurality of high-frequency terminals are provided on a mounting side surface of said multi-layer assembly while lateral sides of said multi-layer assembly are not provided with any electrode for said high-frequency terminals, a multi-layer capacitor ~~which forms~~ forming a part of at least one of said switching circuit ~~and/or~~ and the filtering circuit is being mounted on said multi-layer assembly so that ~~the~~ a direction of stacking layers in said multi-layer assembly extends substantially vertical to ~~the~~ a direction of stacking paired capacitor electrodes provided on layers of said multi-layer capacitor.

16 (currently amended). A high-frequency switching module ~~primarily~~ including a switching circuit and a filtering circuit, comprising:

a multi-layer assembly having a plurality of dielectric sheets of layers placed one over ~~the other~~ another;

a plurality of high-frequency terminals provided on outer surfaces of the multi-layer assembly;

said switching circuit being formed with circuit electrodes in the layers of said multi-layer assembly [[,]] having ~~one~~ a first end thereof connected to a first high-frequency terminal of said plurality of high-frequency terminals; and

said filtering circuit being formed with circuit electrodes in the layers of said multi-layer assembly [[,]] having a first end thereof connected to ~~the other~~ a second end of said switching

circuit ~~and the other~~, a second end thereof being connected to a second high-frequency terminal of said plurality of high-frequency terminals,

wherein said plurality of high-frequency terminals are provided on a mounting side surface of said multi-layer assembly while lateral sides of said multi-layer assembly are not provided with any electrode for said plurality of high-frequency terminals, a chip inductor ~~which~~ forming a part of at least one of said switching circuit ~~and/or~~ and the filtering circuit is being mounted on said multi-layer assembly so that ~~the~~ an axis of electrode coils in said chip inductor extends substantially vertical to ~~the~~ an axis of a spiral transmission line which forms a part of said at least one of said switching circuit ~~and/or~~ and the filtering circuit in said multi-layer assembly.

17 (canceled).

18 (canceled).

19 (currently amended). Δ The high-frequency switching module according to claim 17, including a switching circuit and a filtering circuit, comprising:

a multi-layer assembly having a plurality of dielectric sheets of layers placed one over another;

a plurality of high-frequency terminals provided on outer surfaces of the multi-layer assembly;

said switching circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a first high-frequency terminal of said plurality of high-frequency terminals;  
and

said filtering circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a second end of said switching circuit, a second end thereof being connected to a second high-frequency terminal of said plurality of high-frequency terminals,

wherein a strip line which forms a part of said switching circuit and/or the filtering circuit is partially located in said multi-layer assembly while the remaining part of the strip line is located on a circuit board on which said multi-layer assembly is mounted, wherein the an  
impedance of the strip line located in the multi-layer assembly is being smaller than ~~the~~ an  
impedance of the strip line located on the circuit board, so that ~~the~~ a total electric length is not greater than  $\lambda/4$ .